



Wide Band Gap for Power Converters (SiC / GaN vs Si)

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Agenda

- Introduction - Power Challenges
- Wide Band Gap (GaN / SiC)
- Measurements
 - Challenges
 - Solutions
- Summary

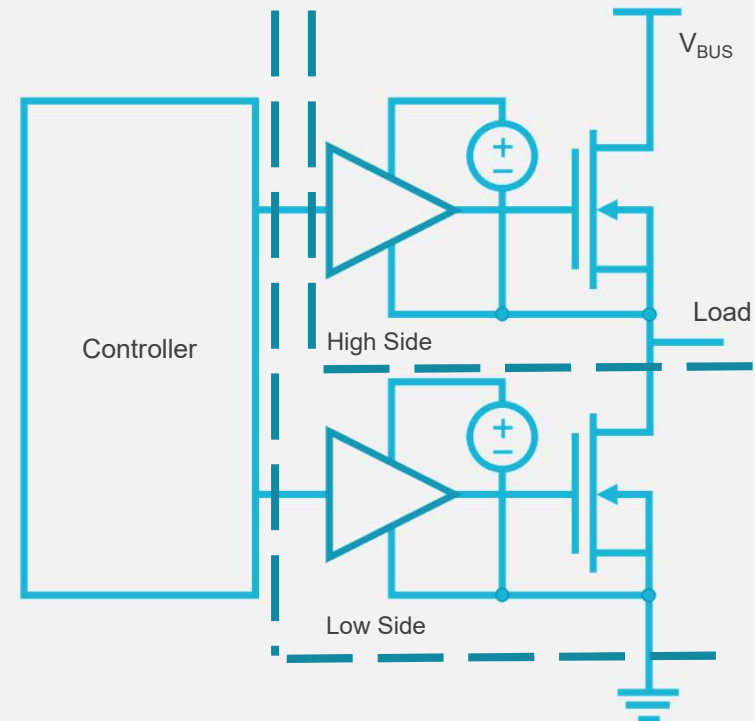
Why Sic and Gan vs Si?

EFFICIENCY
POWER DENSITY
Reliability
Stability
Cost
Weight
SIZE

Traditional Circuit Gets Complicated

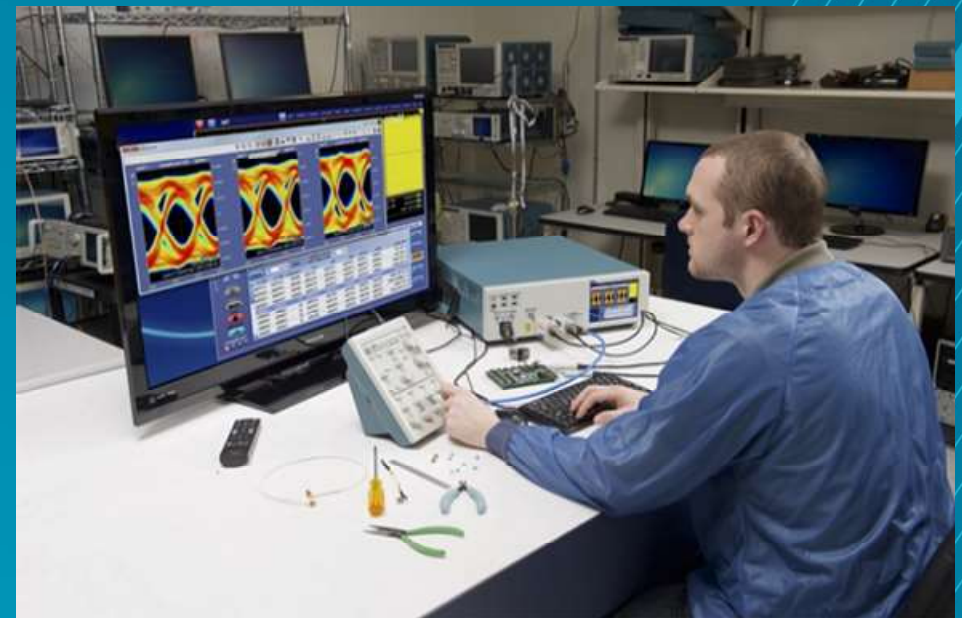
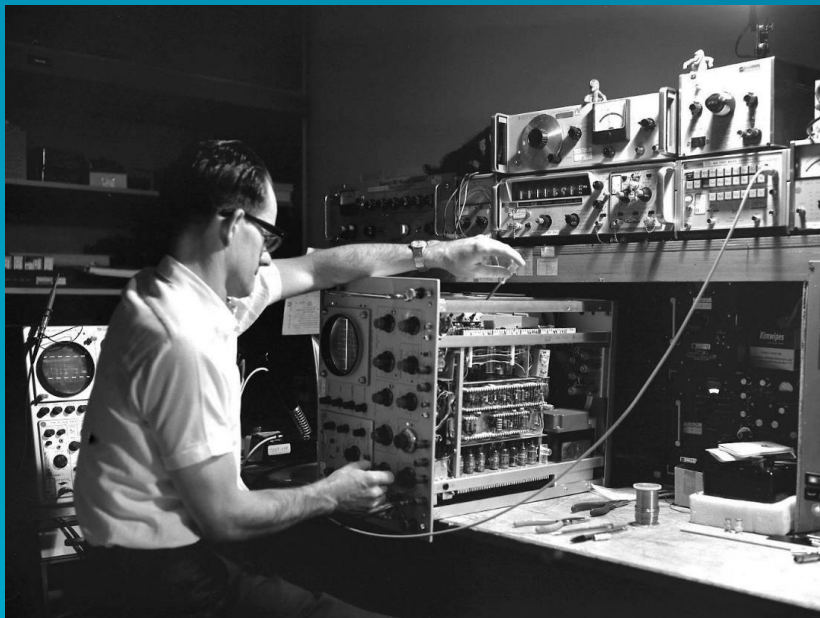
THE HALF BRIDGE

- Demands for higher efficiency
- Increased voltages and currents
- Smaller size
- Environmental tolerance
- Cost
- Reliability



Technology is Changing

Wide Band Gap (GaN / SiC)



Introduction of Wide Band Gap (GaN / SiC)

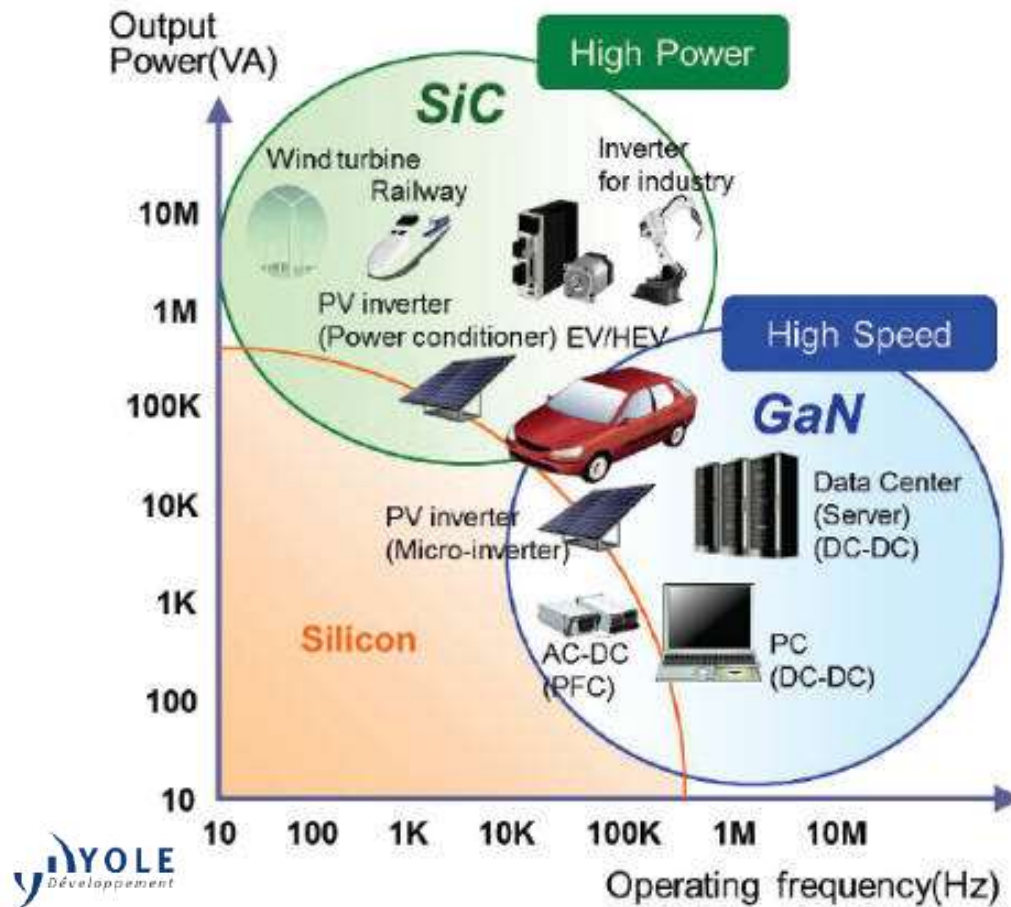
- GaN: Gallium Nitride
- SiC: Silicon Carbide

Compared to conventional semiconductor materials like Silicon (Si) and Gallium Arsenide (GaAs) wide-bandgap semiconductors allow:

- Operation at much higher voltage/current
- Operation at higher temperatures
- Operation at higher frequencies
- Smaller packaging



Power vs. Switching Speeds

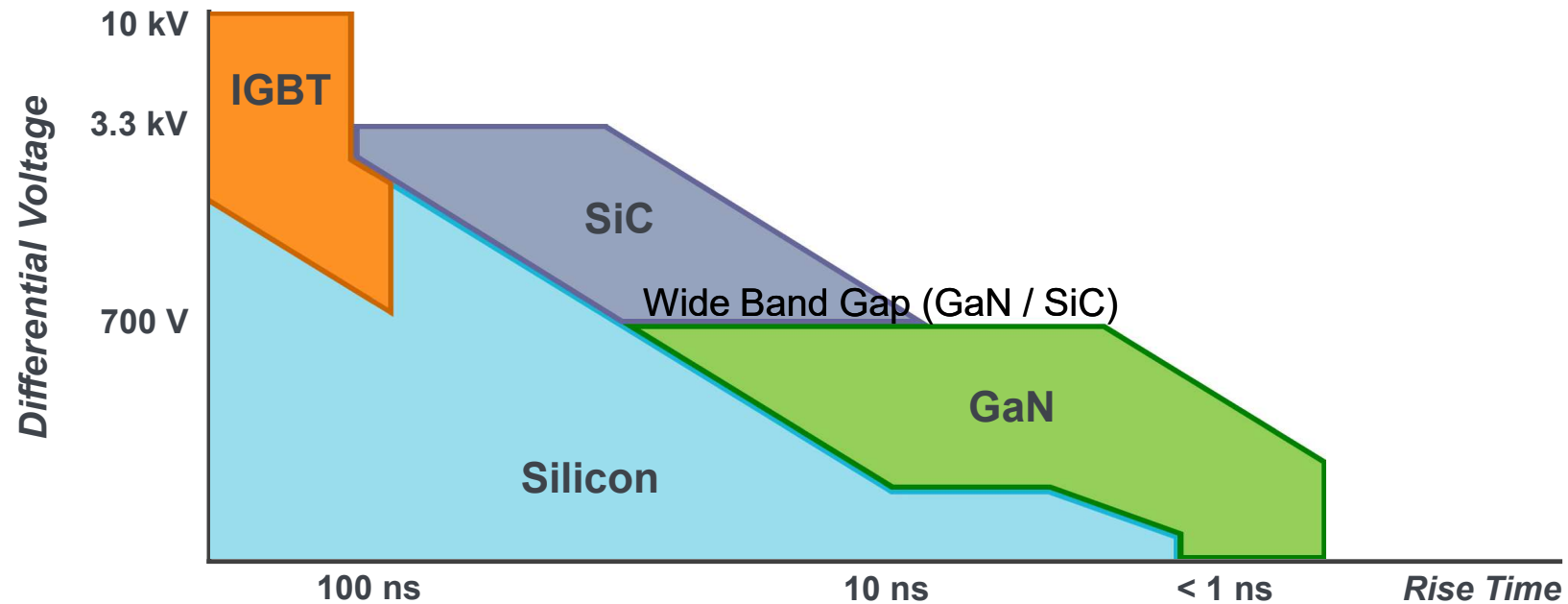


SiC for high power voltages (>1kV) with high current
= niche market

GaN on Si for high frequency at midrange voltages (<1kV, up to 100A)
= mass market

More Than Just Switching Frequency

FOCUSING ON RISETIMES



Measurement Challenges



Wide Band Gap: Measurement Challenges

Fast high voltage fast switching

- Common mode rejection

Fast rise times

- Measurement bandwidth

Sensitivity to **parasitics**

- Measurements that don't **effect** the design

Accessibility to test points

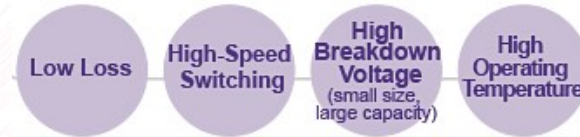
- Connecting to the small model sizes

Safety

- Injury or death



Challenges (headaches) with WBG



- Alternative **packaging** materials
- EMI
- New **designs**, new architectures
- PCB **layout**
- **Integration** with existing systems or **new Gate Driver**
- **Reliability and Robustness**
- \$\$\$

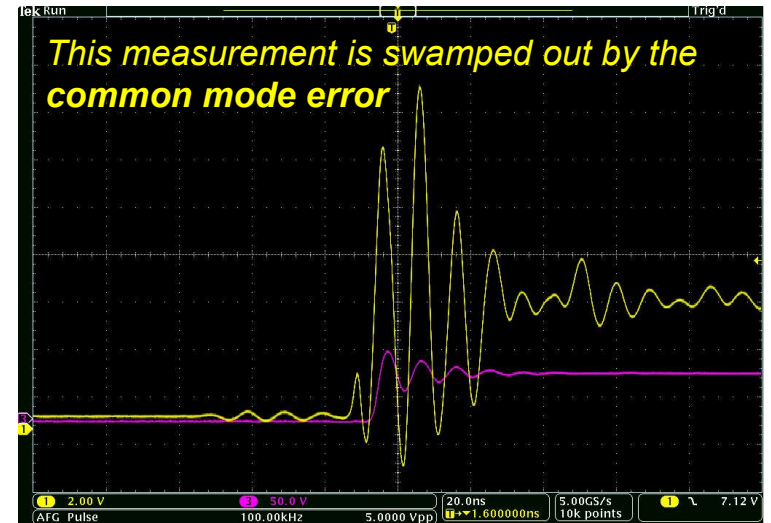
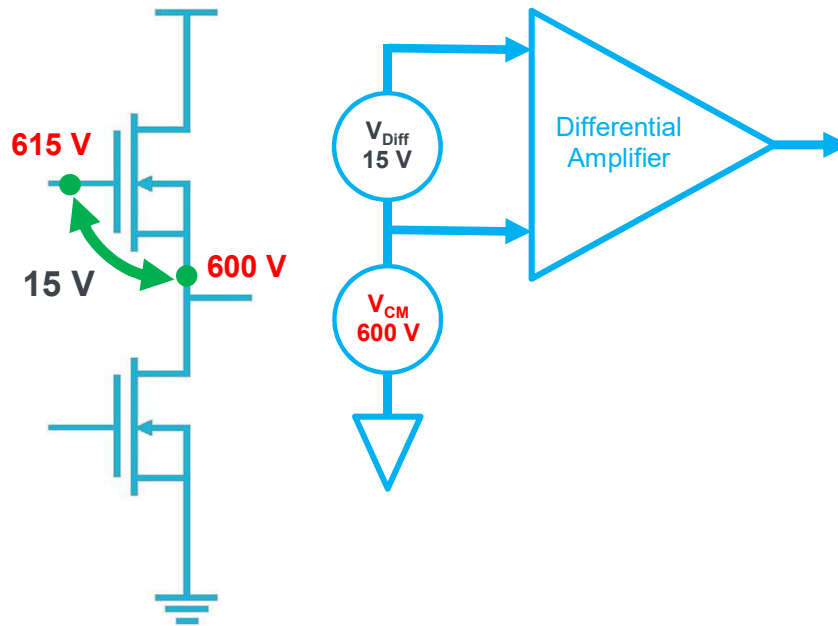
- **Simulate & Measure**



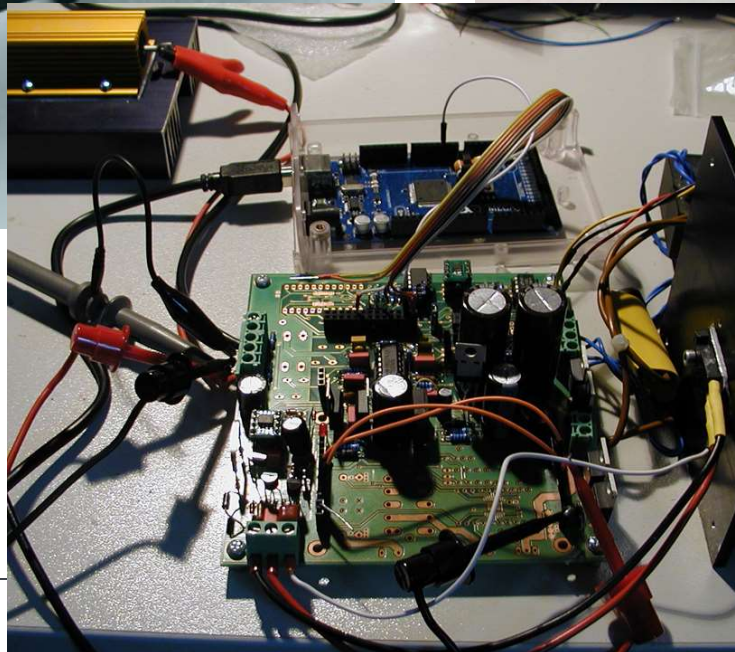
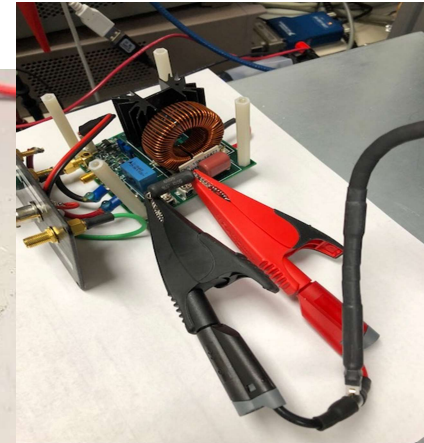
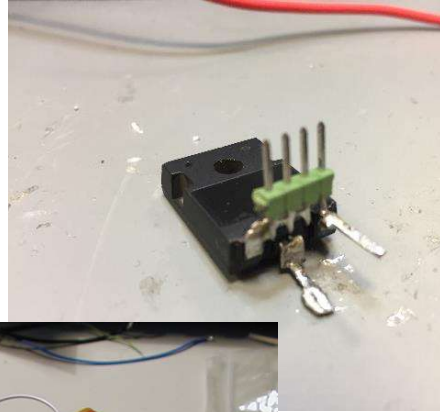
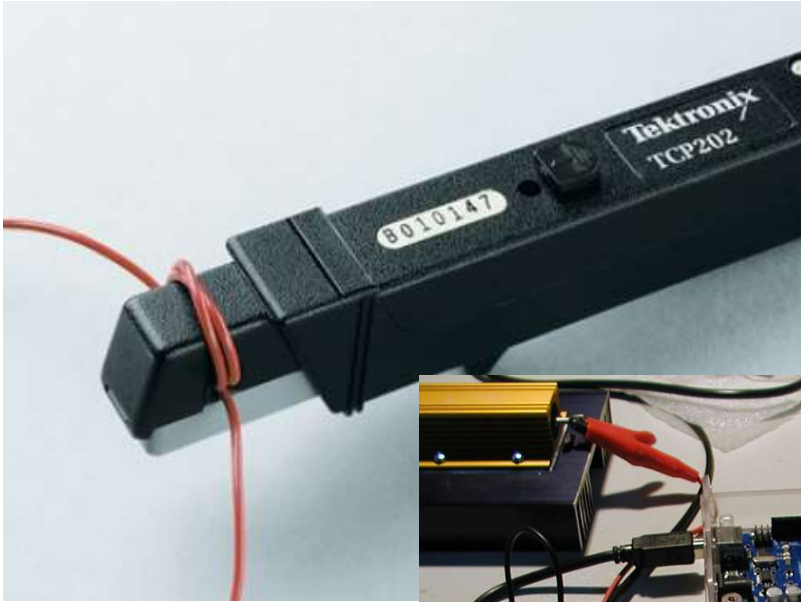
High Side Measurement Challenge

REJECTING COMMON MODE VOLTAGE INDUCED ERRORS

- Isolation from ground
- Fast hi-fidelity measurement system

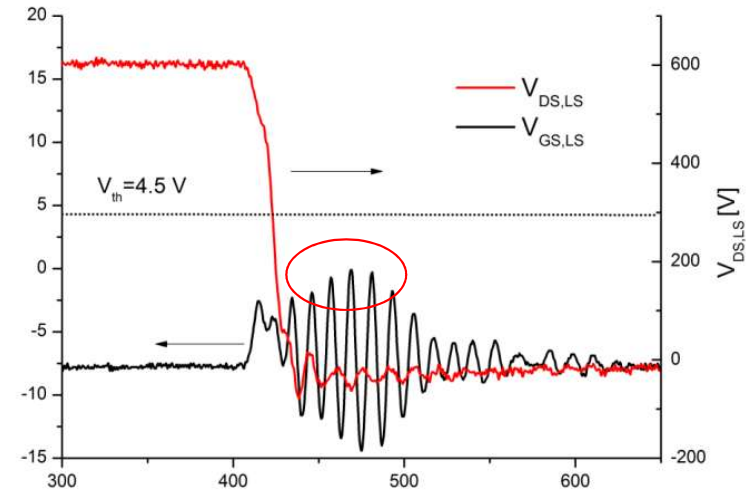
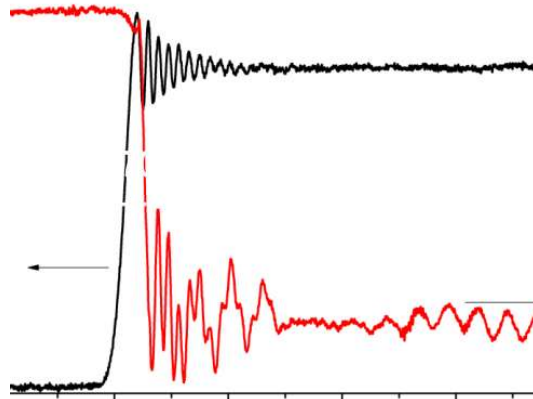
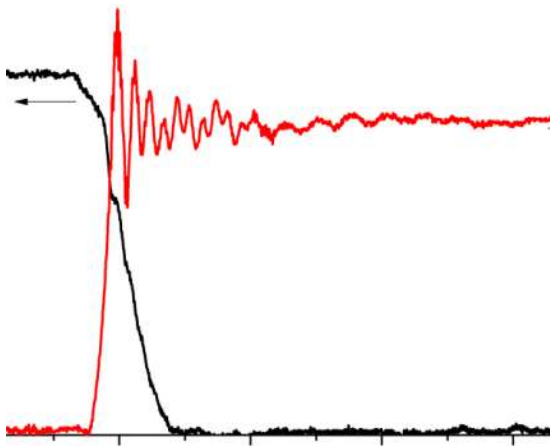


Connections



Switching **faster** (and its consequences)

High Switching Speed (dv/dt and di/dt) - **Oscillations**



Shoot-through?

Real? Or measurement artifact?

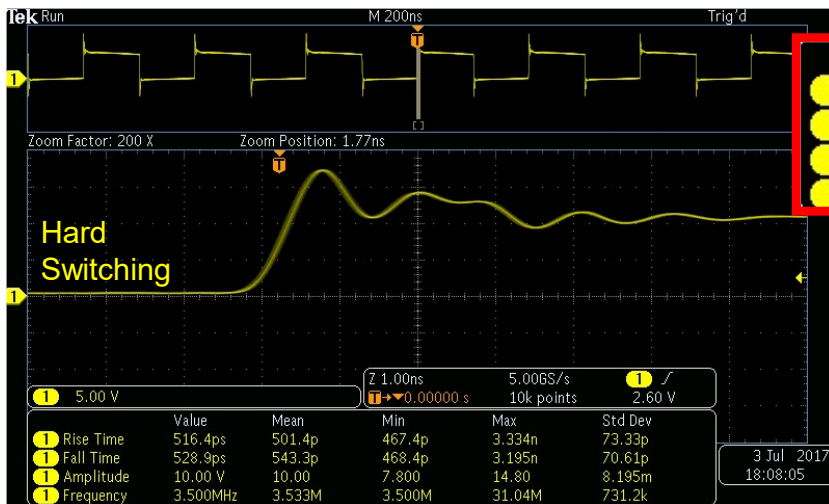
From Infineon [Presentation](#)



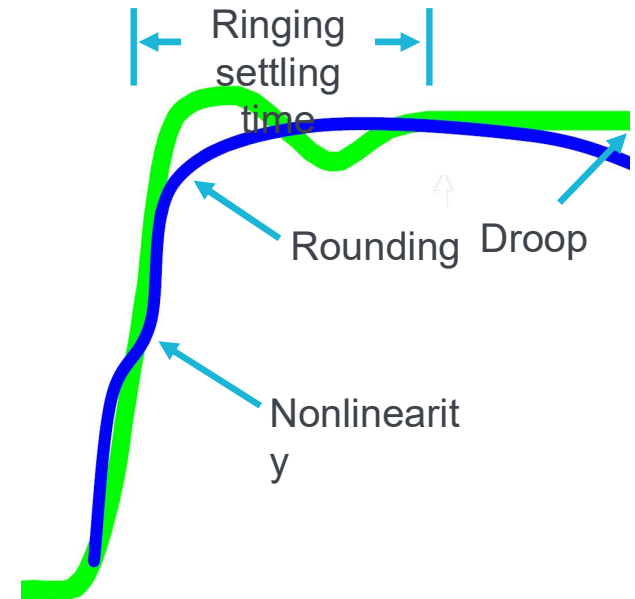
Bandwidth and Rise Time Considerations

RISE TIME, NOT SWITCHING SPEED

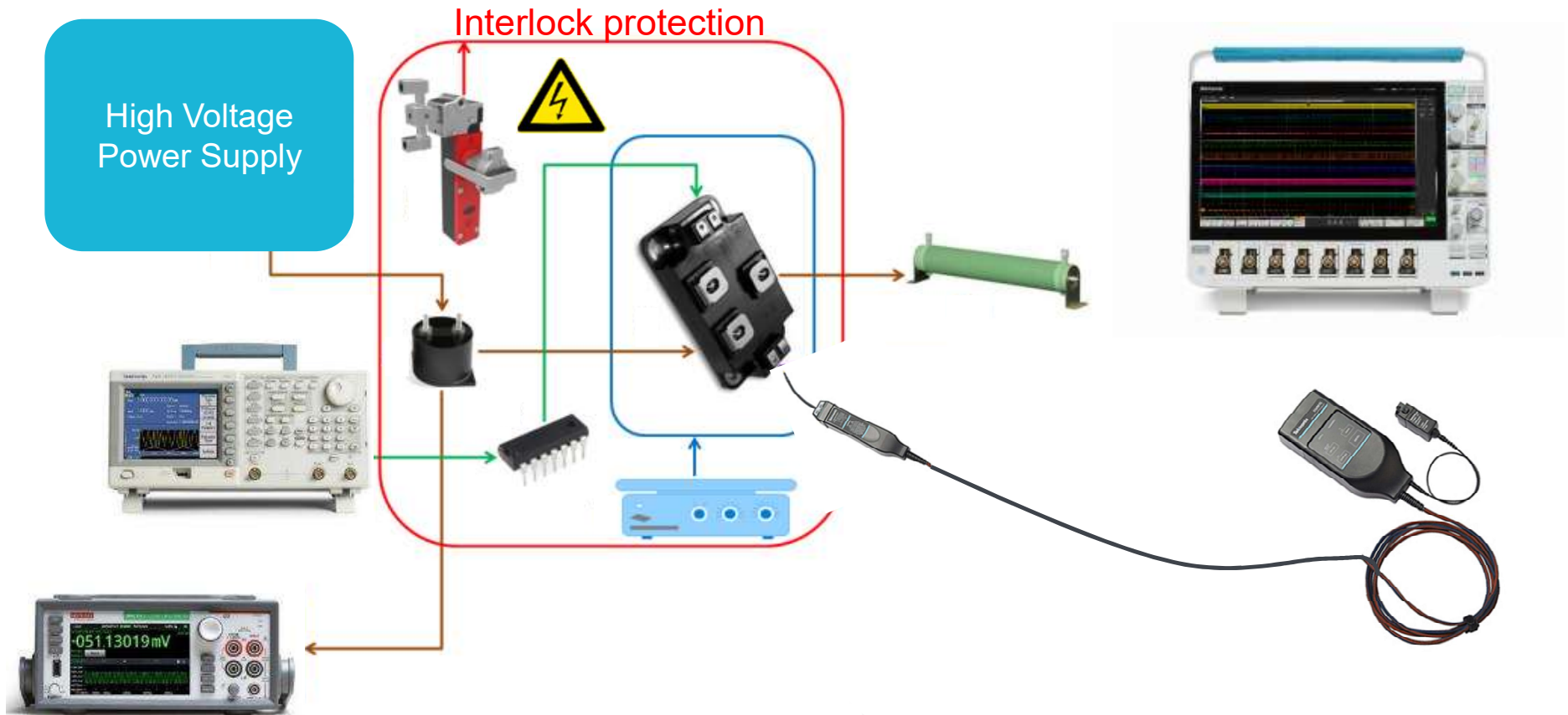
- Edge rate
- Ringing
- Sharp transients



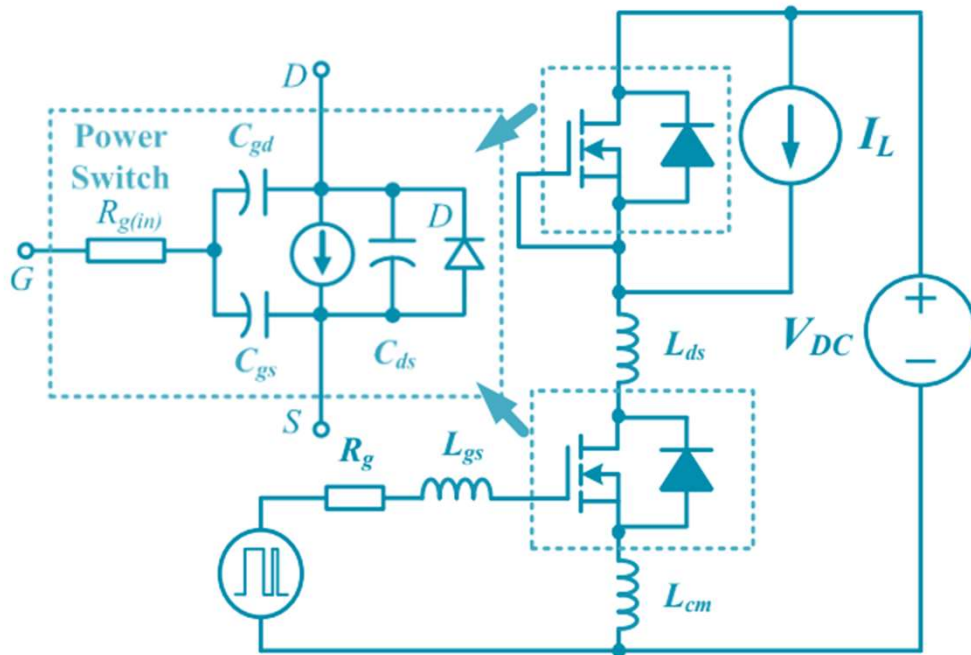
Parameter	Value
Rise Time	516.4ps
Fall Time	528.9ps
Amplitude	10.00 V
Frequency	3.500MHz



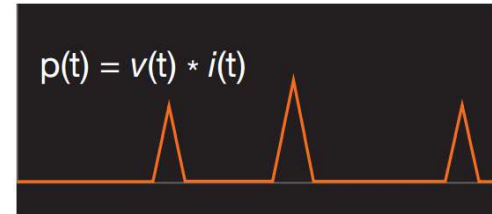
Safety: High voltage precautions



Switching losses and deskew



Switch Voltage and Current

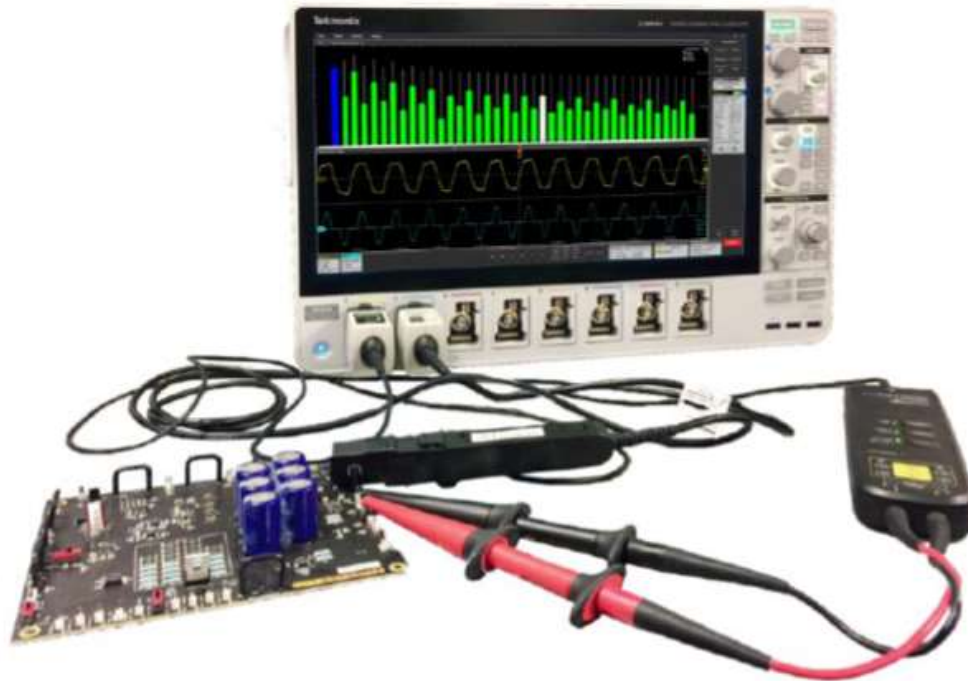


Switch Power Loss



Connection Fidelity and Safety

ISSUES WITH THIS SETUP FOR WBG?



SiC Vgs High Side Comparision



Recap in a nutshell



Fast switching -> more parasitic

Reduce current loops, reduce resonances

Accurate measurements rely on using suitable instruments (for that specific measurement)

Instrument starts at the probe tip

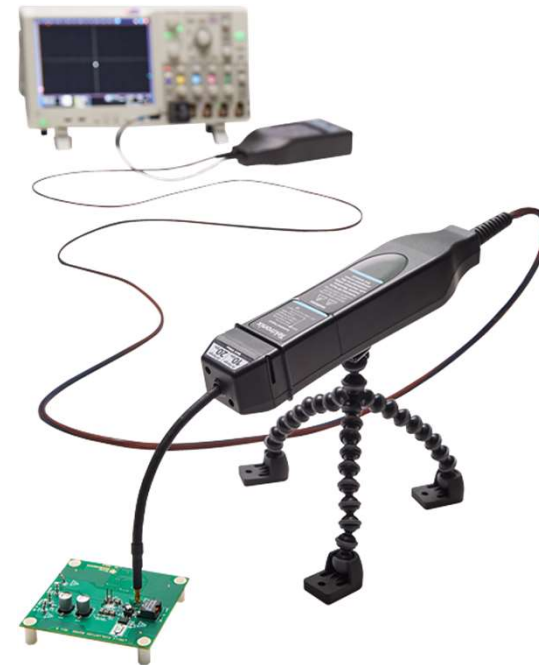
Instruments always influence measurements

Stay safe

IsoVu Probing Technology

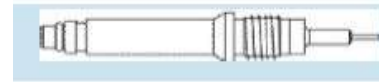
IsoVu™ technology is a radically new high voltage isolated differential probing solution that gives **Accurate** and **Repeatable** results

- Galvanically isolates the device-under-test from a Tektronix oscilloscope.
- **1 GHz** bandwidth
- World's best common mode rejection
 - Up to **160 dB** (100 million to 1)
- **> 2.5 kV differential** voltage range
- **60 kV** common mode voltage range
- Up to **40 MΩ** input resistance



MMCX For Isovu And Passive Probes

HI-FIDELITY, SAFE, RELIABLE



206-0663-xx

Tip mates directly with MMCX connector



- Shielded, low inductance connection to test points
- Secure hands-free connectivity
- Uses low-cost, industry-standard MMCX connectors
- MMCX connectors may be "tacked on" and used as unplanned test points

Adapters connect to standard-pitch pins



- Two adapters available for connecting to square pins
 - Spaced on 0.1 in. (2.54 mm) centers
 - Spaced on 0.062 in. (1.57 mm) centers
- Solder tool available for placing 0.062 in. pins

"Y" leads connect to non-standard-pitch pins



- Y-lead adapter works with the 0.1 in. adapter

Tripod mount for added stability

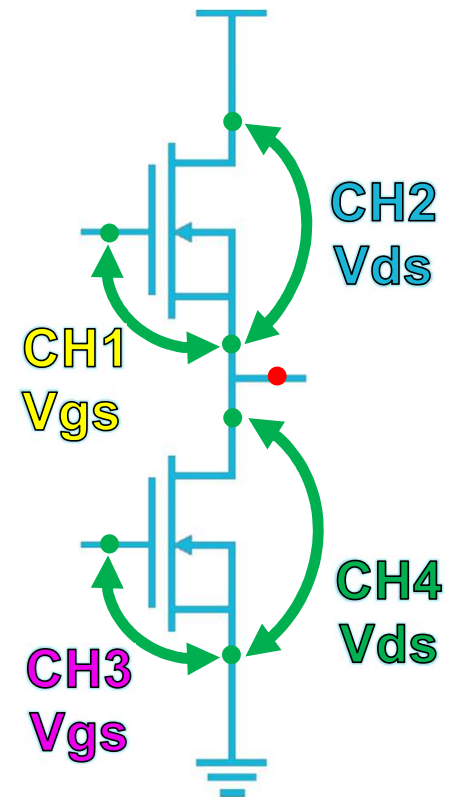
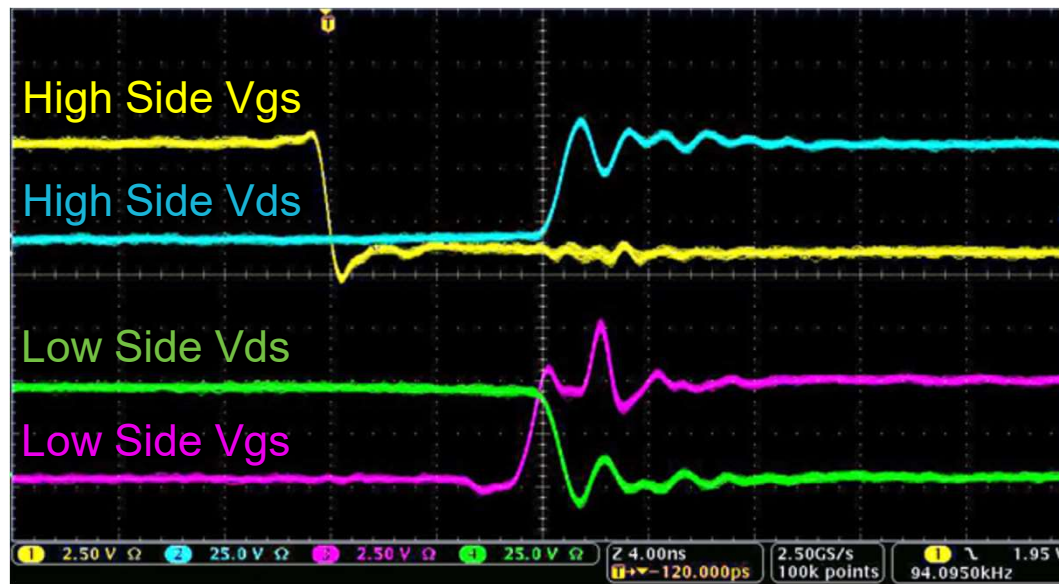


- Tripod mount adds stability to square-pin mounted probes
- Tripod may be glued down to the PCB

Characterize the Entire Switching Circuit

IT IS CRITICAL TO SEE THESE TEST POINTS

- Characterize the gate voltages, V_{ds} , and I_s
- Characterize the time alignment of high and low side events
- Optimize and tune switching characteristics





Thank You

